Single 2-Input NOR Gate

The MC74HC1G02 is a high-speed CMOS 2-input NOR gate fabricated with silicon gate CMOS technology.

The internal circuit is composed of multiple stages, including a buffer output which provides high noise immunity and stable output.

The MC74HC1G02 output drive current is 1/2 compared to the MC74HC series.

- High Speed: $t_{PD} = 7 \text{ ns (Typ)}$ at $V_{CC} = 5 \text{ V}$
- Low Power Dissipation: $I_{CC} = 1 \mu A \text{ (Max)}$ at $T_A = 25 \text{ °C}$
- High Noise Immunity
- Balanced Propagation Delays (t_{PLH} = t_{PHL})
- Symmetrical Output Impedance ($I_{OH} = I_{OL} = 2 \text{ mA}$)
- Chip Complexity: FET = 40

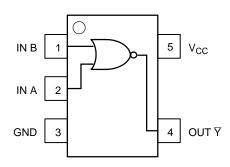


Figure 1. Pinout (Top View)

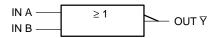


Figure 2. Logic Symbol



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MARKING DIAGRAMS



SC70-5/SC-88A/SOT-353 DF SUFFIX CASE 419A





SOT23-5/TSOP-5/SC59-5 DT SUFFIX CASE 483



d = Date Code

PIN ASSIGNMENT						
1	IN B					
2	IN A					
3	GND					
4	OUT ₹					
5	V _{CC}					

FUNCTION TABLE

Inpu	Output			
Α	A B			
L	L	Н		
L	Н	L		
Н	L	L		
Н	Н	L		

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 4 of this data sheet.

MAXIMUM RATINGS

Symbol		Parameter	Value	Unit
V _{CC}	DC Supply Voltage		-0.5 to +7.0	V
V _{IN}	DC Input Voltage		-0.5 to V_{CC} $+0.5$	V
V _{OUT}	DC Output Voltage		-0.5 to $V_{CC} + 0.5$	V
I _{IK}	DC Input Diode Current		±20	mA
I _{OK}	DC Output Diode Current		±20	mA
I _{OUT}	DC Output Sink Current	± 12.5	mA	
I _{CC}	DC Supply Current per Supply Pin	± 25	mA	
T _{STG}	Storage Temperature Range	-65 to +150	°C	
TL	Lead Temperature, 1 mm from Cas	e for 10 Seconds	260	°C
TJ	Junction Temperature Under Bias		+150	°C
θ_{JA}	Thermal Resistance	SC70–5/SC–88A (Note 1) TSOP–5	350 230	°C/W
P _D	Power Dissipation in Still Air at 85°	C SC70-5/SC-88A TSOP-5	150 200	mW
MSL	Moisture Sensitivity		Level 1	
F _R	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V-0 @ 0.125 in	
V _{ESD}	ESD Withstand Voltage	Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4)	> 2000 > 200 N/A	V
I _{LATCH-UP}	Latch-Up Performance	Above V _{CC} and Below GND at 125°C (Note 5)	±500	mA

Maximum Ratings are those values beyond which damage to the device may occur. Exposure to these conditions or conditions beyond those indicated may adversely affect device reliability. Functional operation under absolute—maximum—rated conditions is not implied. Functional operation should be restricted to the Recommended Operating Conditions.

- 1. Measured with minimum pad spacing on an FR4 board, using 10 mm-by-1 inch, 20 ounce copper trace with no air flow.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- 4. Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	DC Supply Voltage	2.0	6.0	V
V _{IN}	DC Input Voltage	0.0	V _{CC}	V
V _{OUT}	DC Output Voltage	0.0	V _{CC}	V
T _A	Operating Temperature Range	-55	+ 125	°C
t _r , t _f	Input Rise and Fall Time $ \begin{array}{c} V_{CC}=2.\\ V_{CC}=3.\\ V_{CC}=4.\\ V_{CC}=6.0 \end{array} $	0 V 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	1000 600 500 400	ns

DEVICE JUNCTION TEMPERATURE VERSUS TIME TO 0.1% BOND FAILURES

Junction Temperature °C	Time, Hours	Time, Years
80	1,032,200	117.8
90	419,300	47.9
100	178,700	20.4
110	79,600	9.4
120	37,000	4.2
130	17,800	2.0
140	8,900	1.0

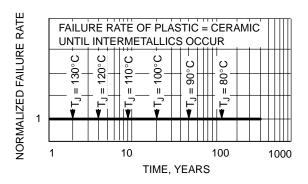


Figure 3. Failure Rate vs. Time Junction Temperature

DC ELECTRICAL CHARACTERISTICS

			V _{CC}	1	T _A = 25°(;	$T_A \leq$	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Conditions	(V)	Min	Тур	Max	Min	Max	Min	Max	Unit
V _{IH}	Minimum High-Level Input Voltage		2.0 3.0 4.5 6.0	1.5 2.1 3.15 4.20			1.5 2.1 3.15 4.20		1.5 2.1 3.15 4.20		V
V _{IL}	Maximum Low-Level Input Voltage		2.0 3.0 4.5 6.0			0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80		0.5 0.9 1.35 1.80	V
V _{OH}	Minimum High–Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OH} = -20 \mu\text{A}$	2.0 3.0 4.5 6.0	1.9 2.9 4.4 5.9	2.0 3.0 4.5 6.0		1.9 2.9 4.4 5.9		1.9 2.9 4.4 5.9		V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OH} = -2$ mA $I_{OH} = -2.6$ mA	4.5 6.0	4.18 5.68	4.31 5.80		4.13 5.63		4.08 5.58		
V _{OL}	Maximum Low–Level Output Voltage V _{IN} = V _{IH} or V _{IL}	$V_{IN} = V_{IH} \text{ or } V_{IL}$ $I_{OL} = 20 \mu\text{A}$	2.0 3.0 4.5 6.0		0.0 0.0 0.0 0.0	0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1		0.1 0.1 0.1 0.1	V
		$V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 2$ mA $I_{OL} = 2.6$ mA	4.5 6.0		0.17 0.18	0.26 0.26		0.33 0.33		0.40 0.40	
I _{IN}	Maximum Input Leakage Current	$V_{IN} = 6.0 \text{ V or GND}$	6.0			± 0.1		±1.0		±1.0	μΑ
Icc	Maximum Quiescent Supply Current	$V_{IN} = V_{CC}$ or GND	6.0			1.0		10		40	μΑ

AC ELECTRICAL CHARACTERISTICS (Input $t_r = t_f = 6.0 \text{ ns}$)

				1	T _A = 25°(C	T _A ≤	85°C	-55°C ≤ 1	T _A ≤ 125°C	
Symbol	Parameter	Test Cor	ditions	Min	Тур	Max	Min	Max	Min	Max	Unit
t _{PLH} ,	Maximum	V _{CC} = 5.0 V	C _L = 15 pF		3.5	15		20		25	ns
t _{PHL}	Propagation Delay, Input A or B to Y	V _{CC} = 2.0 V	$C_1 = 50 \text{ pF}$		19	100		125		155	
	Input A of B to 1	$V_{CC} = 3.0 \text{ V} $ $V_{CC} = 4.5 \text{ V} $			10.5	27		35		90	
		$V_{CC} = 4.5 \text{ V}$			7.5	20		25		35	
		$V_{CC} = 6.0 \text{ V}$			6.5	17		21		26	
t _{TLH} ,	Output Transition	V _{CC} = 5.0 V	C _L = 15 pF		3	10		15		20	ns
t _{THL}	Time	V _{CC} = 2.0 V	$C_1 = 50 \text{ pF}$		25	125		155		200	
		$V_{CC} = 3.0 \text{ V} $ $V_{CC} = 4.5 \text{ V}$			16	35		45		60	
		$V_{CC} = 4.5 \text{ V}$			11	25		31		38	
		$V_{CC} = 6.0 \text{ V}$			9	21		26		32	
C _{IN}	Maximum Input Capacitance				5	10		10		10	pF

		Typical @ 25°C, V _{CC} = 5.0 V	
C_{PD}	Power Dissipation Capacitance (Note 6)	10	pF

^{6.} C_{PD} is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: $I_{CC(OPR)} = C_{PD} \bullet V_{CC} \bullet f_{in} + I_{CC}$. C_{PD} is used to determine the no–load dynamic power consumption; $P_D = C_{PD} \bullet V_{CC}^2 \bullet f_{in} + I_{CC} \bullet V_{CC}$.

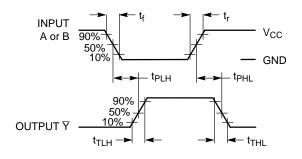
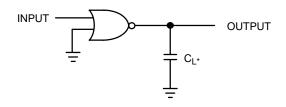


Figure 4. Switching Waveforms



*Includes all probe and jig capacitance. A 1–MHz square input wave is recommended for propagation delay tests.

Figure 5. Test Circuit

DEVICE ORDERING INFORMATION

	Device Nomenclature							
Device Order Number	Logic Circuit Indicator	Temp Range Identifier	Range Device Package Reel		Tape and Reel Suffix	Package Type (Name/SOT#/ Common Name)	Tape and Reel Size	
MC74HC1G02DFT1	МС	74	HC1G	02	DF	T1	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G02DFT2	МС	74	HC1G	02	DF	T2	SC70-5/SC-88A/ SOT-353	178 mm (7 in) 3000 Unit
MC74HC1G02DTT1	МС	74	HC1G	02	DT	T1	SOT23-5/TSOP-5/ SC59-5	178 mm (7 in) 3000 Unit

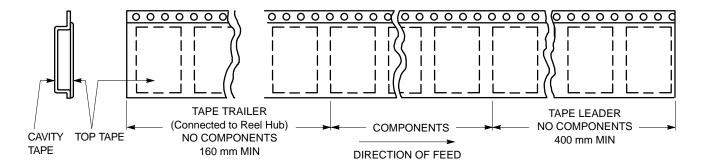


Figure 6. Tape Ends for Finished Goods

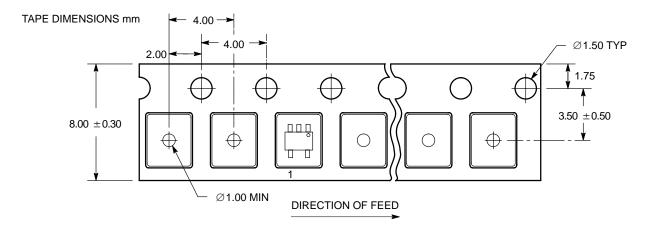


Figure 7. DFT1 Reel Configuration/Orientation

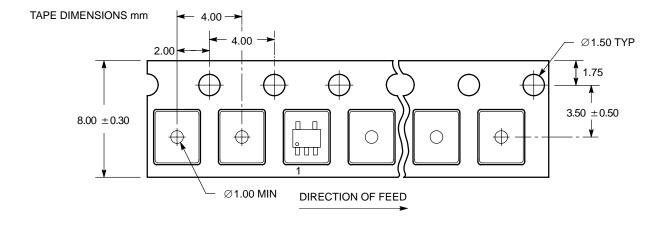


Figure 8. DFT2/DTT1 Reel Configuration/Orientation

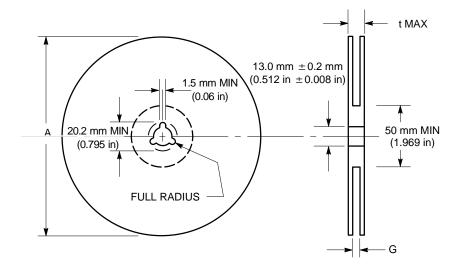


Figure 9. Reel Dimensions

REEL DIMENSIONS

Tape Size	Tape and Reel Suffix	A Max	G	t Max
8 mm	T1, T2		8.4 mm, +1.5 mm, -0.0 (0.33 in + 0.059 in, -0.00)	14.4 mm (0.56 in)

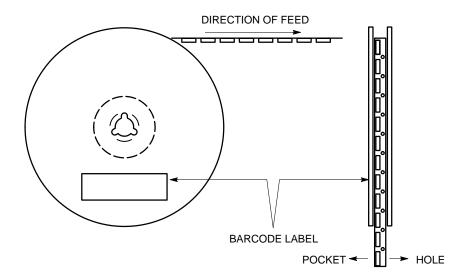
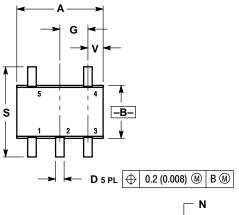


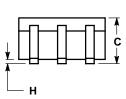
Figure 10. Reel Winding Direction

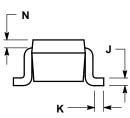
PACKAGE DIMENSIONS

SC70-5/SC-88A/SOT-353 **DF SUFFIX**

5-LEAD PACKAGE CASE 419A-01 ISSUE E

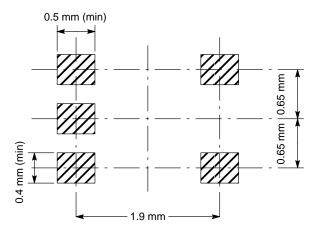






- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

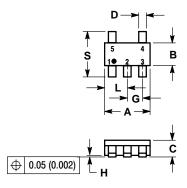
	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.071	0.087	1.80	2.20	
В	0.045	0.053	1.15	1.35	
C	0.031	0.043	0.80	1.10	
D	0.004	0.012	0.10	0.30	
G	0.026	BSC	0.65 BSC		
Н		0.004		0.10	
J	0.004	0.010	0.10	0.25	
K	0.004	0.012	0.10	0.30	
N	0.008 REF		0.20	REF	
S	0.079	0.087	2.00	2.20	
٧	0.012	0.016	0.30	0.40	

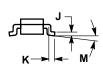


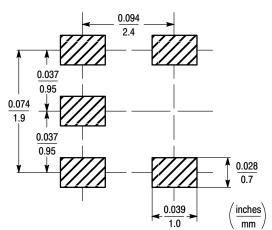
PACKAGE DIMENSIONS

SOT23-5/TSOP-5/SC59-5 **DT SUFFIX**

5-LEAD PACKAGE CASE 483-01 ISSUE A







NOTES

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
- MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.1142	0.1220
В	1.30	1.70	0.0512	0.0669
С	0.90	1.10	0.0354	0.0433
D	0.25	0.50	0.0098	0.0197
G	0.85	1.00	0.0335	0.0413
Н	0.013	0.100	0.0005	0.0040
J	0.10	0.26	0.0040	0.0102
K	0.20	0.60	0.0079	0.0236
L	1.25	1.55	0.0493	0.0610
М	0 °	10°	0°	10°
S	2.50	3.00	0.0985	0.1181

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